1200V 20A SiC Schottky MPS[™] Diode

Silicon Carbide Schottky Diode



| V _{RRM} | = | 1200 V |
|-----------------------------|---|--------|
| I _{F (Tc = 135°C)} | = | 32 A |
| Qc | = | 47 nC |

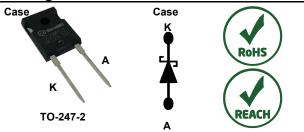
Features

- High Avalanche (UIS) Capability
- Enhanced Surge Current Capability
- Superior Figure of Merit Q_C/I_F
- Low Thermal Resistance
- 175 °C Maximum Operating Temperature
- Temperature Independent Switching Behavior
- Positive Temperature Coefficient of V_F
- Extremely Fast Switching Speeds

Advantages

- Low Standby Power Losses
- Improved Circuit Efficiency (Lower Overall Cost)
- Low Switching Losses
- Ease of Paralleling without Thermal Runaway
- Smaller Heat Sink Requirements
- Low Reverse Recovery Current
- Low Device Capacitance
- Low Reverse Leakage Current





Applications

- Boost Diode in Power Factor Correction (PFC)
- Switched Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Motor Drives
- Freewheeling / Anti-parallel Diode in Inverters
- Solar Inverters & Wind Energy Converters
- Electric Vehicles (EV) & DC Fast Charging
- Induction Heating & Welding

Absolute Maximum Ratings (At T_c = 25 °C Unless Otherwise Stated)

| Parameter | Symbol | Conditions | Values | Unit | |
|--------------------------------------------------------------|-----------------------------------|-------------------------------------------------|------------|------------------|--|
| Repetitive Peak Reverse Voltage | V _{RRM} | | 1200 | V | |
| | | T _C = 25 °C, D = 1 | 67 | | |
| Continuous Forward Current | I _F | T _C = 135 °C, D = 1 | 32 | А | |
| | | T _C = 155 °C, D = 1 | 20 | | |
| Non-Repetitive Peak Forward Surge Current, Half Sine Wave | I _{F,SM} | T _C = 25 °C, t _P = 10 ms | 160 | ٨ | |
| | | T _C = 150 °C, t _P = 10 ms | 128 | A | |
| Repetitive Peak Forward Surge Current, Half Sine Wave | I _{F,RM} | T _C = 25 °C, t _P = 10 ms | 96 | ٨ | |
| | | T _C = 150 °C, t _P = 10 ms | 68 | A | |
| Non-Repetitive Peak Forward Surge Current | I _{F,max} | T _C = 25 °C, t _P = 10 μs | 800 | А | |
| i ² t Value | ∫i ² dt | T _C = 25 °C, t _P = 10 ms | 128 | A ² s | |
| Non-Repetitive Avalanche Energy | E _{AS} | L = 1.3 mH, I _{AS} = 20 A | 245 | mJ | |
| Diode Ruggedness | dV/dt | V _R = 0 ~ 960 V | 200 | V/ns | |
| Power Dissipation | P _{tot} | T _C = 25 °C | 312 | W | |
| Operating and Storage Temperature | T _j , T _{stg} | | -55 to 175 | °C | |



Electrical Characteristics

| Parameter | Sympol | Conditions | | Values | | | 11 |
|-------------------------|----------------|-----------------------------------------------------------|--------------------------------------------------|--------|------|------|------|
| | Symbol | | | Min. | Тур. | Max. | Unit |
| Diode Forward Voltage | V | I _F = 20 A, T _j = 25 °C | | | 1.5 | 1.8 | V |
| | V _F | I _F = 20 A, T _j = 175 °C | | | 2 | 2.4 | |
| Reverse Current | I | V _R = 1200 V, T _j = 25 °C | | 3 | 15 | | |
| | I _R | V_{R} = 1200 V, T_{j} | V _R = 1200 V, T _j = 175 °C | | 30 | 150 | μA |
| Total Capacitive Charge | 0 | | V _R = 400 V | | 34 | | nC |
| | Q _C | $I_F \leq I_{F,MAX}$ | V _R = 800 V | | 47 | | |
| Switching Time | + | dl _F /dt = 200 A/µs T _j = 175 °C | V _R = 400 V | | < 10 | | 20 |
| | t _s | | V _R = 800 V | | < 10 | | ns |
| Total Capacitance | C | V _R = 1 V, f = 1 MHz | | | 1079 | | |
| | С | V _R = 800 V, f = 1 MHz | | | 70 | pF | |

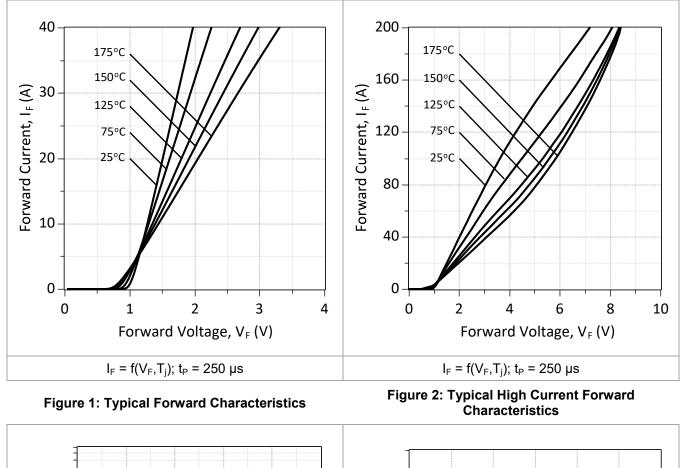
Thermal / Mechanical Characteristics

| Thermal Resistance, Junction - Case | R _{thJC} | | 0.48 | °C/W |
|-------------------------------------|-------------------|----------|------|------|
| Weight | W _T | | 6 | g |
| Mounting Torque | T _M | M3 Screw | 1.1 | Nm |



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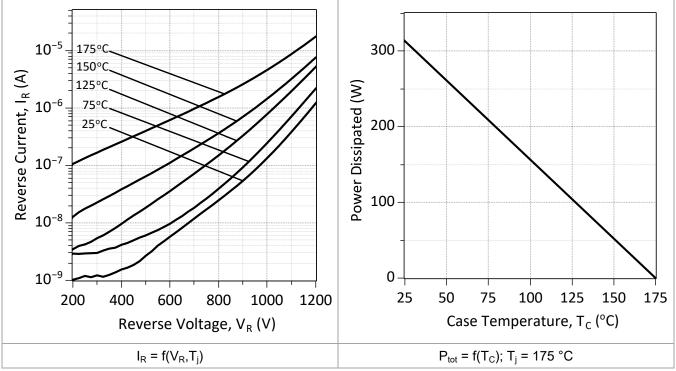
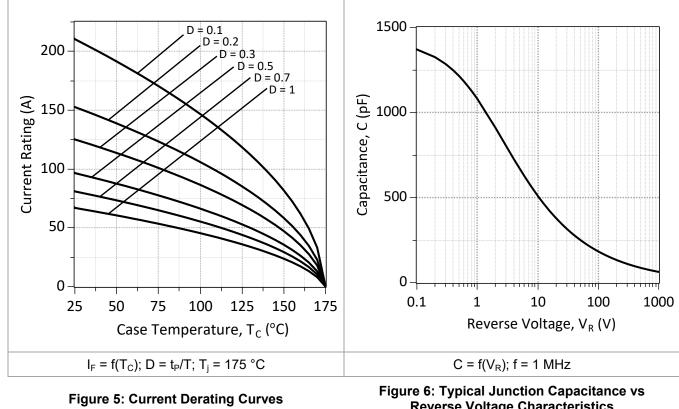


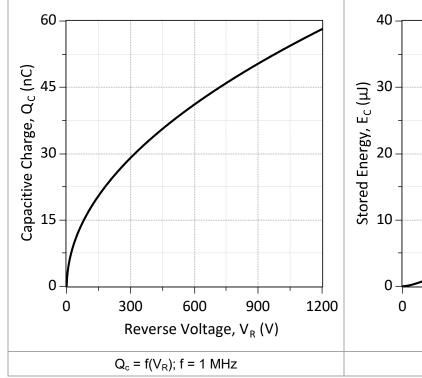


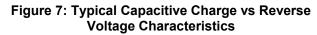
Figure 4: Power Derating Curve

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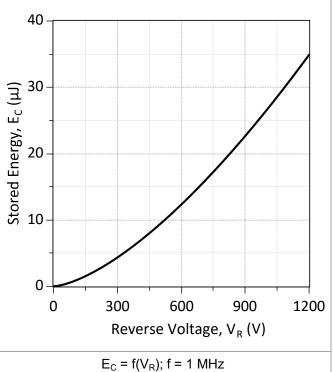


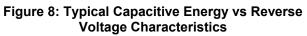




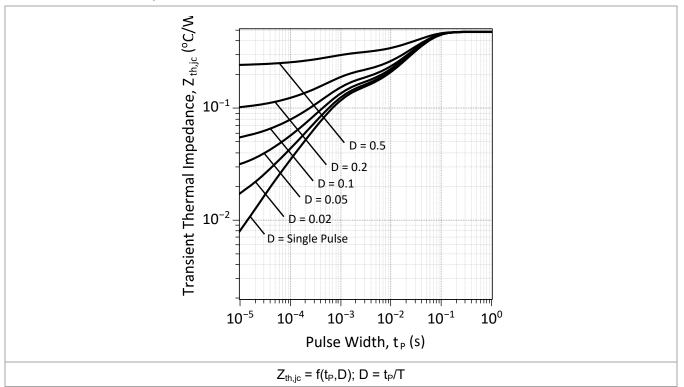




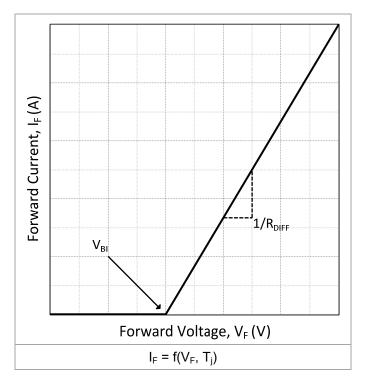


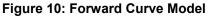


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 $I_{F} = (V_{F} - V_{BI})/R_{DIFF} (A)$

Built-In Voltage (V_{BI}):

$$V_{BI}(T_j) = m^*T_j + n (V),$$

m = -1.48e-03, n = 1.08

Differential Resistance (R_{DIFF}):

$$R_{DIFF}(T_j) = a^*T_j^2 + b^*T_j + c(\Omega);$$

CTOF

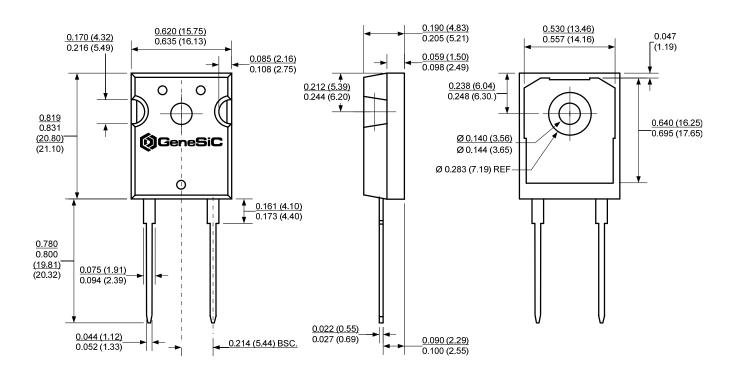
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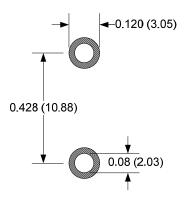
Package Dimensions

TO-247-2

Package Outline



Recommended Solder Pad Layout



NOTE

- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
- 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

GB20SLT12-247 1200V 20A SiC Schottky MPS[™] Diode



RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS 2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863. RoHS Declarations for this product can be obtained from your GeneSiC representative.

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Related Links

- SPICE Models: https://www.genesicsemi.com/schottky-mps
- Evaluation Boards: https://www.genesicsemi.com/technical-support
- Quality Manual: https://www.genesicsemi.com/technical-support/quality-manual
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